

Data sheet Product ICK SMD B 19 MI



Heatsinks and active heatsinks for processors>Heatsinks for DIL-IC, PLCC and SMD

19 x 4,8 mm, for SMD components and others

Features

width:	19 mm
height:	4.8 mm
plate thickness:	1 mm
length:	19 mm
thermal resistance:	22 K/W
surface:	solderable surface

Technical Drawing

